



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	16
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.25V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f530a-im

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

14.2.2. External Crystal Example	139
14.2.3. External RC Example	141
14.2.4. External Capacitor Example	141
14.3. System Clock Selection	143
15. UART0	144
15.1. Enhanced Baud Rate Generation	145
15.2. Operational Modes	146
15.2.1. 8-Bit UART	146
15.2.2. 9-Bit UART	147
15.3. Multiprocessor Communications	148
16. Enhanced Serial Peripheral Interface (SPI0)	151
16.1. Signal Descriptions	152
16.1.1. Master Out, Slave In (MOSI)	152
16.1.2. Master In, Slave Out (MISO)	152
16.1.3. Serial Clock (SCK)	152
16.1.4. Slave Select (NSS)	152
16.2. SPI0 Master Mode Operation	153
16.3. SPI0 Slave Mode Operation	154
16.4. SPI0 Interrupt Sources	155
16.5. Serial Clock Timing	156
16.6. SPI Special Function Registers	156
17. LIN (C8051F520/0A/3/3A/6/6A and C8051F530/0A/3/3A/6/6A)	164
17.1. Software Interface with the LIN Peripheral	165
17.2. LIN Interface Setup and Operation	165
17.2.1. Mode Definition	165
17.2.2. Baud Rate Options: Manual or Autobaud	165
17.2.3. Baud Rate Calculations—Manual Mode	165
17.2.4. Baud Rate Calculations—Automatic Mode	168
17.3. LIN Master Mode Operation	169
17.4. LIN Slave Mode Operation	170
17.5. Sleep Mode and Wake-Up	171
17.6. Error Detection and Handling	171
17.7. LIN Registers	172
17.7.1. LIN Direct Access SFR Registers Definition	172
17.7.2. LIN Indirect Access SFR Registers Definition	174
18. Timers	182
18.1. Timer 0 and Timer 1	182
18.1.1. Mode 0: 13-bit Counter/Timer	182
18.1.2. Mode 1: 16-bit Counter/Timer	184
18.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload	184
18.1.4. Mode 3: I wo 8-bit Counter/Timers (Timer 0 Only)	185
18.2. Timer 2	190
18.2.1. 16-bit Timer with Auto-Reload	190
1822 8-bit Limers with Auto-Reload	
	191













1.2. CIP-51[™] Microcontroller

1.2.1. Fully 8051 Compatible Instruction Set

The C8051F52x/F52xA/F53x/F53xA devices use Silicon Laboratories' proprietary CIP-51 microcontroller core. The CIP-51 is fully compatible with the MCS-51[™] instruction set. Standard 803x/805x assemblers and compilers can be used to develop software. The C8051F52x/F52xA/F53x/F53xA family has a superset of all the peripherals included with a standard 8052.

1.2.2. Improved Throughput

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12-to-24 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.

With the CIP-51's system clock running at 25 MHz, it has a peak throughput of 25 MIPS. The CIP-51 has a total of 109 instructions. The table below shows the total number of instructions that require each execution time.

Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8
Number of Instructions	26	50	5	14	7	3	1	2	1

1.2.3. Additional Features

The C8051F52x/F52xA/F53x/F53xA family includes several key enhancements to the CIP-51 core and peripherals to improve performance and ease of use in end applications.

An extended interrupt handler allows the numerous analog and digital peripherals to operate independently of the controller core and interrupt the controller only when necessary. By requiring less intervention from the microcontroller core, an interrupt-driven system is more efficient and allows for easier implementation of multi-tasking, real-time systems.

Eight reset sources are available: power-on reset circuitry (POR), an on-chip V_{DD} monitor, a Watchdog Timer, a Missing Clock Detector, a voltage level detection from Comparator, a forced software reset, an external reset pin, and an illegal Flash access protection circuit. Each reset source except for the POR, Reset Input Pin, or Flash error may be disabled by the user in software. The WDT may be permanently enabled in software after a power-on reset during MCU initialization.

The internal oscillator is factory calibrated to 24.5 MHz $\pm 0.5\%$ across the entire operating temperature and voltage range. An external oscillator drive circuit is also included, allowing an external crystal, ceramic resonator, capacitor, RC, or CMOS clock source to generate the system clock.

1.2.4. On-Chip Debug Circuitry

The C8051F52x/F52xA/F53x/F53xA devices include on-chip Silicon Laboratories 2-Wire (C2) debug circuitry that provides non-intrusive, full speed, in-circuit debugging of the production part *installed in the end application*.

Silicon Laboratories' debugging system supports inspection and modification of memory and registers, breakpoints, and single stepping. No additional target RAM, program memory, timers, or communications channels are required. All the digital and analog peripherals are functional and work correctly while debugging. All the peripherals (except for the ADC) are stalled when the MCU is halted, during single stepping, or at a breakpoint in order to keep them synchronized.

The C8051F530DK development kit provides all the hardware and software necessary to develop application code and perform in-circuit debugging with the C8051F52x/F52xA/F53x/F53xA MCUs. The kit



Name	Pin Nur	nbers	Туре	Description
	'F52xA 'F52x-C	'F52x		
P0.3/TX*/	—	8	D I/O or A In	Port 0.3. See Port I/O Section for a complete description.
XTAL2			D I/O	External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. See Section "14. Oscillators" on page 135.
P0.2	9	9	D I/O or	Port 0.2. See Port I/O Section for a complete description.
XTAL1			A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. Section "14. Oscillators" on page 135.
P0.1/	10	10	D I/O or A In	Port 0.1. See Port I/O Section for a complete description.
C2D			D I/O	Bi-directional data signal for the C2 Debug Interface
Note: Please	refer to Se	ection "2	20. Device S	Specific Behavior" on page 210.

Table 3.1. Pin Definitions for the C8051F52x and C8051F52xA (DFN 10) (Continued)





Figure 3.3. DFN-10 Landing Diagram

C1 2.90 E 0.50 E X1 0.20 X2 1.70 Y1 0.70 Y2 2.45 Notes: General 1. All dimensions shown are in millimeters (mm) unless 2. This land pattern design is based on the IPC-7351 g Solder Mask Design 3. All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design 4. A stainless steel, laser-cut and electro-polished stem should be used to assure good solder paste release 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land pad size should	3.00 3SC.
E 0.50 E X1 0.20 X2 1.70 Y1 0.70 Y2 2.45 Notes: General 1. All dimensions shown are in millimeters (mm) unless 2. This land pattern design is based on the IPC-7351 g Solder Mask Design 3. All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design 4. A stainless steel, laser-cut and electro-polished stem should be used to assure good solder paste release 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land pad size should	SSC.
X1 0.20 X2 1.70 Y1 0.70 Y2 2.45 Notes: General 1. All dimensions shown are in millimeters (mm) unless 2. This land pattern design is based on the IPC-7351 g Solder Mask Design 3. All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design 4. A stainless steel, laser-cut and electro-polished steen should be used to assure good solder paste release 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land pad size should	
X2 1.70 Y1 0.70 Y2 2.45 Notes: General 1. All dimensions shown are in millimeters (mm) unless 2. This land pattern design is based on the IPC-7351 g Solder Mask Design 3. All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design 4. A stainless steel, laser-cut and electro-polished sten should be used to assure good solder paste release 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land pad size should	0.30
Y1 0.70 Y2 2.45 Notes: General 1. All dimensions shown are in millimeters (mm) unless 2. This land pattern design is based on the IPC-7351 g Solder Mask Design 3. All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design 4. A stainless steel, laser-cut and electro-polished steen should be used to assure good solder paste release 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land nad size should	1.80
Y2 2.45 Notes: General 1. All dimensions shown are in millimeters (mm) unless 2. This land pattern design is based on the IPC-7351 g Solder Mask Design 3. All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design 4. A stainless steel, laser-cut and electro-polished steen should be used to assure good solder paste release 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land pad size should	0.80
 Notes: <u>General</u> All dimensions shown are in millimeters (mm) unless This land pattern design is based on the IPC-7351 g Solder Mask Design All metal pads are to be non-solder mask defined (N between the solder mask and the metal pad is to be way around the pad. Stencil Design A stainless steel, laser-cut and electro-polished sten should be used to assure good solder paste release The stencil thickness should be 0.125 mm (5 mils). 	2.55
 A stainless steel, laser-cut and electro-polished stem should be used to assure good solder paste release The stencil thickness should be 0.125 mm (5 mils). The ratio of stencil aperture to land pad size should 	guidelines. ISMD). Clearance 60 µm minimum, all the
 pads. 7. A 4x1 array of 1.60 x 0.45 mm openings on 0.65 mm the center ground pad. Card Assembly 	ncil with trapezoidal walls be 1:1 for all perimeter

9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.





Figure 3.7. QFN-20 Pinout Diagram (Top View)



4. 12-Bit ADC (ADC0)

The ADC0 on the C8051F52x/F52x/F53x/F53x/F53xA Family consists of an analog multiplexer (AMUX0) with 16/6 total input selections, and a 200 ksps, 12-bit successive-approximation-register (SAR) ADC with integrated track-and-hold, programmable window detector, programmable gain, and hardware accumulator. The ADC0 subsystem has a special Burst Mode which can automatically enable ADC0, capture and accumulate samples, then place ADC0 in a low power shutdown mode without CPU intervention. The AMUX0, data conversion modes, and window detector are all configurable under software control via the Special Function Registers shown in Figure 4.1. ADC0 inputs are single-ended and may be configured to measure P0.0-P1.7, the Temperature Sensor output, V_{DD} , or GND with respect to GND. The voltage reference for the ADC is selected as described in Section "5. Voltage Reference" on page 72. ADC0 is enabled when the AD0EN bit in the ADC0 Control register (ADC0CN) is set to logic 1, or when performing conversions in Burst Mode. ADC0 is in low power shutdown when AD0EN is logic 0 and no Burst Mode conversions are taking place.



Figure 4.1. ADC0 Functional Block Diagram

4.1. Analog Multiplexer

AMUX0 selects the input channel to the ADC. Any of the following may be selected as an input: P0.0–P1.7, the on-chip temperature sensor, the core power supply (V_{DD}), or ground (GND). **ADC0 is single-ended and all signals measured are with respect to GND.** The ADC0 input channels are selected using the ADC0MX register as described in SFR Definition 4.4.

Important Note About ADC0 Input Configuration: Port pins selected as ADC0 inputs should be configured as analog inputs, and should be skipped by the Digital Crossbar. To configure a Port pin for analog input, set to 0 the corresponding bit in register PnMDIN (for n = 0,1). To force the Crossbar to skip a Port pin, set to 1 the corresponding bit in register PnSKIP (for n = 0,1). See Section "13. Port Input/Output" on page 120 for more Port I/O configuration details.



4.4.1. Calculating the Gain Value

The ADC0 selectable gain feature is controlled by 13 bits in three registers. ADC0GNH contains the 8 upper bits of the gain value and ADC0GNL contains the 4 lower bits of the gain value. The final GAINADD bit (ADC0GNA.0) controls an optional extra 1/64 (0.016) of gain that can be added in addition to the ADC0GNH and ADC0GNL gain. The ADC0GNA.0 bit is set to 1 after a power-on reset.

The equivalent gain for the ADC0GNH, ADC0GNL and ADC0GNA registers is:

$$gain = \left(\frac{GAIN}{4096}\right) + GAINADD \times \left(\frac{1}{64}\right)$$

Equation 4.2. Equivalent Gain from the ADC0GNH and ADC0GNL Registers

Where:

GAIN is the 12-bit word of ADC0GNH[7:0] and ADC0GNL[7:4] *GAINADD* is the value of the GAINADD bit (ADC0GNA.0) *gain* is the equivalent gain value from 0 to 1.016

For example, if ADC0GNH = 0xFC, ADC0GNL = 0x00, and GAINADD = '1', GAIN = 0xFC0 = 4032, and the resulting equation is:

$$gain = \left(\frac{4032}{4096}\right) + 1 \times \left(\frac{1}{64}\right) = 0.984 + 0.016 = 1.0$$

The table below equates values in the ADC0GNH, ADC0GNL, and ADC0GNA registers to the equivalent gain using this equation.

ADC0GNH Value	ADC0GNL Value	GAINADD Value	GAIN Value	Equivalent Gain
0xFC (default)	0x00 (default)	1 (default)	4032 + 64	1.0 (default)
0x7C	0x00	1	1984 + 64	0.5
0xBC	0x00	1	3008 + 64	0.75
0x3C	0x00	1	960 + 64	0.25
0xFF	0xF0	0	4095 + 0	~1.0
0xFF	0xF0	1	4095 + 64	1.016

For any desired gain value, the GAIN registers can be calculated by:

$$GAIN = \left(gain - GAINADD \times \left(\frac{1}{64}\right)\right) \times 4096$$

Equation 4.3. Calculating the ADC0GNH and ADC0GNL Values from the Desired Gain Where:

GAIN is the 12-bit word of ADC0GNH[7:0] and ADC0GNL[7:4] *GAINADD* is the value of the GAINADD bit (ADC0GNA.0) *gain* is the equivalent gain value from 0 to 1.016

When calculating the value of GAIN to load into the ADC0GNH and ADC0GNL registers, the GAINADD bit can be turned on or off to reach a value closer to the desired gain value.



SFR Definition 4.4. ADC0MX: ADC0 Channel Select

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-			ADUMX			00011111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xBB
Bits7_5.	UNUSED R	ad – 00)0h· Write – c	lon't care				
Bits4–0:		AMUX0	Positive Inpu	ut Selection	า			
	AD0MX4–0		ADC0 Input	Channel				
	00000		P0.0					
	00001		P0.1					
	00010		P0.2					
	00011		P0.3					
	00100	00 P0.4						
	00101		P0.5					
	00110		P0.6*					
	00111		P0.7*					
	01000		P1.0*					
	01001		P1.1*					
	01010		P1.2*					
	01011		P1.3*					
	01100		P1.4*					
	01101		P1.5*					
	01110		P1.6*					
	01111		P1.7*					
	11000		Temp Senso	or				
	11001		V _{DD}					
	11010 1111	1						



4.5. Programmable Window Detector

The ADC Programmable Window Detector continuously compares the ADC0 output registers to user-programmed limits, and notifies the system when a desired condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (AD0WINT in register ADC0CN) can also be used in polled mode. The ADC0 Greater-Than (ADC0GTH, ADC0GTL) and Less-Than (ADC0LTH, ADC0LTL) registers hold the comparison values. The window detector flag can be programmed to indicate when measured data is inside or outside of the user-programmed limits, depending on the contents of the ADC0 Less-Than and ADC0 Greater-Than registers.

SFR Definition 4.10. ADC0GTH: ADC0 Greater-Than Data High Byte



SFR Definition 4.11. ADC0GTL: ADC0 Greater-Than Data Low Byte





4.5.1. Window Detector In Single-Ended Mode

Figure 4.7 shows two example window comparisons for right-justified data with ADC0LTH:ADC0LTL = 0x0200 (512d) and ADC0GTH:ADC0GTL = 0x0100 (256d). The input voltage can range from 0 to V_{RFF} x (4095/4096) with respect to GND, and is represented by a 12-bit unsigned integer value. The repeat count is set to one. In the left example, an AD0WINT interrupt will be generated if the ADC0 conversion word (ADC0H:ADC0L) is within the range defined by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL (if 0x0100 < ADC0H:ADC0L < 0x0200). In the right example, and AD0WINT interrupt will be generated if the ADC0 conversion word is outside of the range defined by the ADC0GT and ADC0LT registers (if ADC0H:ADC0L < 0x0100 or ADC0H:ADC0L > 0x0200). Figure 4.8 shows an example using left-justified data with the same comparison values.



Figure 4.7. ADC Window Compare Example: Right-Justified Single-Ended Data



Figure 4.8. ADC Window Compare Example: Left-Justified Single-Ended Data



9. Memory Organization and SFRs

The memory organization of the C8051F52x/F52xA/F53x/F53x/F53xA is similar to that of a standard 8051. There are two separate memory spaces: program memory and data memory. Program and data memory share the same address space but are accessed via different instruction types. The memory map is shown in Figure 9.1.



Figure 9.1. Memory Map

9.1. Program Memory

The CIP-51 core has a 64 kB program memory space. The C8051F520/0A/1/1A and C8051F530/0A/1/1A implement 8 kB of this program memory space as in-system, re-programmable Flash memory, organized in a contiguous block from addresses 0x0000 to 0x1FFF. Addresses above 0x1DFF are reserved on the 8 kB devices. The C8051F523/3A/4/4A and C8051F533/3A/4/4A implement 4 kB of Flash from addresses 0x0000 to 0x0FFF. The C8051F526/6A/7/7A and C8051F536/6A/7/7A implement 2 kB of Flash from addresses 0x0000 to 0x07FF.

Program memory is normally assumed to be read-only. However, the C8051F52x/F52xA/F53x/F53xA can write to program memory by setting the Program Store Write Enable bit (PSCTL.0) and using the MOVX write instruction. This feature provides a mechanism for updates to program code and use of the program memory space for non-volatile data storage. Refer to Section "12. Flash Memory" on page 113 for further details.



9.2. Data Memory

The C8051F52x/F52xA/F53x/F53xAincludes 256 bytes of internal RAM mapped into the data memory space from 0x00 through 0xFF. The lower 128 bytes of data memory are used for general purpose registers and scratch pad memory. Either direct or indirect addressing may be used to access the lower 128 bytes of data memory. Locations 0x00 through 0x1F are addressable as four banks of general purpose registers, each bank consisting of eight byte-wide registers. The next 16 bytes, locations 0x20 through 0x2F, may either be addressed as bytes or as 128 bit locations accessible with the direct addressing mode.

The upper 128 bytes of data memory are accessible only by indirect addressing. This region occupies the same address space as the Special Function Registers (SFRs) but is physically separate from the SFR space. The addressing mode used by an instruction when accessing locations above 0x7F determines whether the CPU accesses the upper 128 bytes of data memory space or the SFRs. Instructions that use direct addressing will access the SFR space. Instructions using indirect addressing above 0x7F access the upper 128 bytes of data memory organization of the C8051F52x/F52xA/F53x/F53xA.

9.3. General Purpose Registers

The lower 32 bytes of data memory (locations 0x00 through 0x1F) may be addressed as four banks of general-purpose registers. Each bank consists of eight byte-wide registers designated R0 through R7. Only one of these banks may be enabled at a time. Two bits in the program status word, RS0 (PSW.3) and RS1 (PSW.4), select the active register bank (see description of the PSW in SFR Definition 8.4. PSW: Program Status Word). This allows fast context switching when entering subroutines and interrupt service routines. Indirect addressing modes use registers R0 and R1 as index registers.

9.4. Bit Addressable Locations

In addition to direct access to data memory organized as bytes, the sixteen data memory locations at 0x20 through 0x2F are also accessible as 128 individually addressable bits. Each bit has a bit address from 0x00 to 0x7F. Bit 0 of the byte at 0x20 has bit address 0x00 while bit 7 of the byte at 0x20 has bit address 0x07. Bit 7 of the byte at 0x2F has bit address 0x7F. A bit access is distinguished from a full byte access by the type of instruction used (bit source or destination operands as opposed to a byte source or destination).

The MCS-51[™] assembly language allows an alternate notation for bit addressing of the form XX.B where XX is the byte address and B is the bit position within the byte. For example, the instruction:

MOV C, 22.3h

moves the Boolean value at 0x13 (bit 3 of the byte at location 0x22) into the Carry flag.

9.5. Stack

A programmer's stack can be located anywhere in the 256-byte data memory. The stack area is designated using the Stack Pointer (SP, 0x81) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07. Therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.

9.6. Special Function Registers

The direct-access data memory locations from 0x80 to 0xFF constitute the special function registers (SFRs). The SFRs provide control and data exchange with the CIP-51's resources and peripherals. The CIP-51 duplicates the SFRs found in a typical 8051 implementation as well as implementing additional



Table 9.2. Special Function Registers

Register	Address	Description	Page
ACC	0xE0	Accumulator	89
ADC0CF	0xBC	ADC0 Configuration	65
ADC0CN	0xE8	ADC0 Control	67
ADC0H	0xBE	ADC0	66
ADC0L	0xBD	ADC0	66
ADC0GTH	0xC4	ADC0 Greater-Than Data High Byte	69
ADC0GTL	0xC3	ADC0 Greater-Than Data Low Byte	69
ADC0LTH	0xC6	ADC0 Less-Than Data High Byte	70
ADC0LTL	0xC5	ADC0 Less-Than Data Low Byte	70
ADC0MX	0xBB	ADC0 Channel Select	64
ADC0TK	0xBA	ADC0 Tracking Mode Select	68
В	0xF0	B Register	89
CKCON	0x8E	Clock Control	188
CLKSEL	0xA9	Clock Select	143
CPT0CN	0x9B	Comparator0 Control	78
CPT0MD	0x9D	Comparator0 Mode Selection	80
CPT0MX	0x9F	Comparator0 MUX Selection	79
DPH	0x83	Data Pointer High	87
DPL	0x82	Data Pointer Low	87
EIE1	0xE6	Extended Interrupt Enable 1	102
EIP1	0xF6	Extended Interrupt Priority 1	103
FLKEY	0xB7	Flash Lock and Key	119
IE	0xA8	Interrupt Enable	100
IP	0xB8	Interrupt Priority	101
IT01CF	0xE4	INT0/INT1 Configuration	105
LINADDR	0x92	LIN indirect address pointer	172
LINCF	0x95	LIN master-slave and automatic baud rate selection	173
LINDATA	0x93	LIN indirect data buffer	172
OSCICL	0xB3	Internal Oscillator Calibration	138

SFRs are listed in alphabetical order. All undefined SFR locations are reserved





Figure 13.2. Port I/O Cell Block Diagram



SFR Definition 13.1. XBR0: Port I/O Crossbar Register 0

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	CP0AE	CP0E	SYSCKE	LINE	SPI0E	URT0E	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_
							SFR Address:	: 0xE1
Bit7–6 :	RESERVED	. Read = 00	0b; Must wr	ite 00b.				
Bit5:	CP0AE: Cor	nparator0 A	synchrono	us Output E	nable			
	0: Asynchror	nous CP0 u	navailable	at Port pin.				
	1: Asynchror	nous CP0 re	outed to Po	ort pin.				
Bit4:	CP0E: Comp	parator0 Ou	itput Enabl	е				
	0: CP0 unav	ailable at P	ort pin.					
	1: CP0 route	ed to Port pi	n.					
Bit3:	SYSCKE: /S	YSCLK Ou	tput Enable	Э				
	0: /SYSCLK	unavailable	e at Port pir	า.				
	1: /SYSCLK	output rout	ed to Port p	oin.				
Bit2:	LINE. Lin Ou	utput Enable	е					
Bit1:	SPIOE: SPI I	/O Enable						
	0: SPI I/O ur	navailable a	t Port pins.					
	1: SPI I/O ro	uted to Por	t pins. Note	e that the SP	I can be as	signed eith	er 3 or 4 GP	PIO pins.
Bit0:	URTOE: UAR	RT I/O Outp	out Enable					
	0: UART I/O	unavailable	e at Port pi	า.				
	1: UART TX	0, RX0 rout	ed to Port	oins (P0.3 ar	nd P0.4) or	(P0.4 and I	P0.5).*	
Note: Refe	r to Section "20	. Device Spe	cific Behavi	or" on page 21	10.			



SFR Definition 15.2. SBUF0: Serial (UART0) Port Data Buffer



Table 15.1. Timer Settings for Standard Baud RatesUsing the Internal Oscillator

	Frequency: 2	24.5 MHz					
	TargetBaud RateBaud Rate% Error(bps)		Oscillator Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select)*	T1M*	Timer 1 Reload Value (hex)
	230400	-0.32%	106	SYSCLK	XX	1	0xCB
	115200	-0.32%	212	SYSCLK	XX	1	0x96
	57600	0.15%	426	SYSCLK	XX	1	0x2B
C. D	28800	-0.32%	848	SYSCLK/4	01	0	0x96
C fr	14400	0.15%	1704	SYSCLK / 12	00	0	0xB9
	9600	-0.32%	2544	SYSCLK / 12	00	0	0x96
/S(2400	-0.32%	10176	SYSCLK / 48	10	0	0x96
S) Int	1200	0.15%	20448	SYSCLK / 48	10	0	0x2B

X = Don't care

Note: SCA1–SCA0 and T1M bit definitions can be found in Section 18.1.



SFR Definition 16.3. SPI0CKR: SPI0 Clock Rate

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
SCR7	SCR6	SCR5	SCR4	SCR3	SCR2	SCR1	SCR0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Addres	s: 0xA2
Bits7–0: S	SCR7-SCR	0: SPI0 Clo	ck Rate.					
Т	hese bits d	etermine th	e frequency	of the SCK	output whe	en the SPI0	module is	configured
fo	or master m	ode operat	ion. The SC	CK clock fre	quency is a	divided ver	sion of the	system
С	lock, and is	given in the	e following	equation, w	here SYSC	LK is the sy	stem clock	c frequency
a	ind SPI0CK	R is the 8-b	oit value hel	d in the SPI	OCKR regis	ster.		
		C.	VOOLV					
	freek	=	YSCLK					
	JSCK	$2 \times (SP)$	PIOCKR +	1)				
fo	or 0 <= SPI	0CKR <= 2	55					
Example: If	SYSCLK =	2 MHz and	SPI0CKR	= 0x04,				
		200000	0					
	f_{SCK} =	$=\frac{200000}{2\times(4)}$	$\frac{1}{1}$					
		2 × (4 +	1)					
	f –	200247						
	J_{SCK} –	200K112,						



SFR Definition 18.1. TCON: Timer Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value					
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00000000					
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addrossable					
							SFR Address:	0x88					
Bit7:	TF1: Timer 1	Overflow I	-lag.	_									
	Set by hardv	vare when	Timer 1 ove	rflows. This	flag can b	e cleared by	software bu	ut is auto-					
	0: No Timor	ared when	the CPU ve	ectors to the	limer 1 in	terrupt servi	ce routine.						
	1: Timer 1 has overflowed.												
Bit6:	TR1 : Timer 1 Run Control. 0: Timer 1 disabled.												
	1: Timer 1 er	nabled.											
Bit5:	TF0: Timer C	Overflow I	Flag.	и. т.:	0		()	1					
	Set by hardy	vare when	the CPLLye	rtiows. This	Timer 0 in	e cleared by	Software bu	it is auto-					
	0: No Timer	0 overflow	detected.			ionupi servi	ce routine.						
	1: Timer 0 ha	as overflow	ed.										
Bit4:	TRO: Timer () Run Cont	rol.										
	0: Timer 0 di	sabled.											
D:42.	1: Timer 0 er	habled.											
DILJ.	This flag is s	et by hardw	/are when a	in edge/leve	al of type de	fined by IT1	is detected	lt can be					
	cleared by so	oftware but	is automati	cally cleare	d when the	CPU vector	s to the Exte	ernal Inter-					
	rupt 1 servic	e routine if	IT1 = 1. Wh	nen ÍT1 = 0,	this flag is	set to 1 whe	en INT0 is a	ctive as					
	defined by bi	it IN1PL in I	register IT0	1CF (see S	FR Definition	on 10.5. "IT(01CF: INT0/	INT1 Con-					
D'/0	figuration" or	n page 105).										
Bit2:	This bit solor	t 1 Type Se	lect.	rod INITO in	torrupt will	ha adaa ar l	oval consitiv						
	configured a	ctive low or	high by the	e IN1PL bit	in the IT01	CF register (see SFR	C. INTO 13					
	Definition 10	.5. "IT01C	F: INT0/INT	1 Configura	ation" on pa	age 105).	(
	0: <u>INT0</u> is lev	el triggere	d.										
D:44	1: INT0 is ec	lge triggere	d.										
BITT	This flag is s	i interrupt (et by bardw). Jare when a	n edge/leve	al of type de	fined by IT() is detected	lt can be					
	cleared by so	oftware but	is automati	callv cleare	d when the	CPU vector	s to the Exte	ernal Inter-					
	rupt 0 servic	e routine if	IT0 = 1. Wh	nen ÍT0 = 0,	this flag is	set to 1 whe	en <mark>INT0</mark> is a	ctive as					
	defined by bi	t IN0PL in	register IT0	1CF (see S	FR Definition	on 10.5. "IT(01CF: INT0/	INT1 Con-					
D'/0	figuration" or	n page 105).										
Bitu:	This bit solor	t 0 Type Se	lect.	rod INITO in	torrupt will	ha adaa ar l	oval consitiv						
	configured a	ctive low or	high by the	e INOPL bit	in reaister l	T01CF (see	SFR Defini	tion 10.5.					
	"IT <u>01</u> CF: INT	T0/INT1 Co	nfiguration"	on page 10)5).								
	0: INTO is lev	vel triggere	d.		-								
	1: INT0 is ec	lge triggere	d.										



19.1. PCA Counter/Timer

The 16-bit PCA counter/timer consists of two 8-bit SFRs: PCA0L and PCA0H. PCA0H is the high byte (MSB) of the 16-bit counter/timer and PCA0L is the low byte (LSB). Reading PCA0L automatically latches the value of PCA0H into a "snapshot" register; the following PCA0H read accesses this "snapshot" register. **Reading the PCA0L Register first guarantees an accurate reading of the entire 16-bit PCA0 counter.** Reading PCA0H or PCA0L does not disturb the counter operation. The CPS2-CPS0 bits in the PCA0MD register select the timebase for the counter/timer as shown in Table 19.1.

When the counter/timer overflows from 0xFFFF to 0x0000, the Counter Overflow Flag (CF) in PCA0MD is set to logic 1 and an interrupt request is generated if CF interrupts are enabled. Setting the ECF bit in PCA0MD to logic 1 enables the CF flag to generate an interrupt request. The CF bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software (Note: PCA0 interrupts must be globally enabled before CF interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit in EIE1 to logic 1). Clearing the CIDL bit in the PCA0MD register allows the PCA to continue normal operation while the CPU is in Idle mode.

CPS2	CPS1	CPS0	Timebase
0	0	0	System clock divided by 12
0	0	1	System clock divided by 4
0	1	0	Timer 0 overflow
0	1	1	High-to-low transitions on ECI (max rate = system clock divided by 4)
1	0	0	System clock
1	0	1	External oscillator source divided by 8*

Table 19.1. PCA Timebase Input Options

Note: External clock divided by 8 is synchronized with the system clock.





